

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

VISWANATHAN, et al.

Group Art Unit: Unknown

Filed: Herewith

Examiner: Unknown

Title: WIRE BOND-LESS ELECTRONIC COMPONENT FOR USE WITH AN EXTERNAL
CIRCUIT AND METHOD OF MANUFACTURE

DECLARATION

As a below named inventor, I hereby declare that:

Type of Declaration

This declaration is made in an original application for utility patent.

Inventorship and Specification Identification

My residence, post office address, and citizenship are as stated below next to my name.

I believe that I am an original, first, and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled WIRE BOND-LESS ELECTRONIC COMPONENT FOR USE WITH AN EXTERNAL CIRCUIT AND METHOD OF MANUFACTURE, filed herewith.

Claim of Priority

I hereby claim foreign priority benefits under 35 U.S.C. § 119 of the foreign application(s) for patent, or inventor's certificate(s), or PCT international application(s) designating at least one country other than the United States of America, listed below:

Country

(If PCT indicate "PCT")

Application No.

Filing Date

Title: Wire Bondless Electronic Component For Use With An External
Circuit And Method Of Manufacture
Inventor(s): Viswanathan, Piel, Funk, and Davidson
Declaration

I have also identified below any foreign application(s) for patent, or inventor's certificate(s), or any PCT international application(s) designating at least one country other than the United States of America, filed by me on the same subject matter having a filing date before that of the application of which priority is claimed (if none, write "NONE"):

<u>Country</u> (if PCT indicate "PCT" or NONE)	<u>Application No.</u>	<u>Filing Date</u>
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Acknowledgment of Review of Papers and Duty of Candor

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims thereof.

I acknowledge the duty to disclose information that is material to the examination of this application, in accordance with Title 37, Code of Federal Regulations, section 1.56(a).

Declaration

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Signatures

Full name of first joint inventor: Lakshminarayan Viswanathan

Inventor's signature:

Date:

Country of Citizenship:

Residence (City & State):

Post Office Address:

Lakshminarayan Viswanathan
December 12, 2001
USA
Phoenix, Arizona
16620 S. 18th Way
Phoenix, Arizona 85048

Title: Wire Bondless Electronic Component For Use With An External
Circuit And Method Of Manufacture
Inventor(s): Viswanathan, Piel, Funk, and Davidson
Declaration

Full name of second joint inventor: Pierre-Marie Piel


Inventor's signature:

Date:

Country of Citizenship:

Residence (City & State):

Post Office Address:


12 December 2001

France

Tempe, Arizona

995 E. Baseline Road, #2106

Tempe, Arizona 85283

Full name of third joint inventor: Garry D. Funk

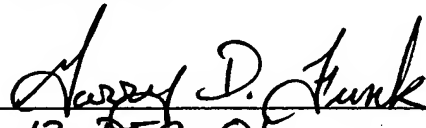
Inventor's signature:

Date:

Country of Citizenship:

Residence (City & State):

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12 DEC 01

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Scottsdale, Arizona

10150 E. Clinton Street

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Full name of fourth joint inventor: Robert Paul Davidson


Inventor's signature:

Date:

Country of Citizenship:

Residence (City & State):

Post Office Address:


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U.S.A.

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Chandler, Arizona 85224

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POWER OF ATTORNEY

Motorola, Inc. is the owner of the above-identified patent, pursuant to an Assignment from the owners of record, Lakshminarayan Viswanathan, Pierre-Marie Piel, Garry D. Funk, and Robert Paul Davidson to Motorola, Inc. executed on December 12, 2001 (the "Assignment"). In accordance with 37 C.F.R. § 3.73(b), a copy of the Assignment is attached hereto. A copy of the Assignment has also been filed or is being filed contemporaneously herewith for recordation with the Assignment Branch.

Motorola, Inc. hereby revokes all previous powers of attorney and appoints George C. Chen, Reg. No. 39,935; Maurice B. Stiefel, Reg. No. 18,479; Lawrence G. Kurland, Reg. No. 24,895; Stephen P. Gilbert, Reg. No. 27,893; David A. Roodman, Reg. No. 35,663; N. Whitney Wilson, Reg. No. 38,661; Daniel A. Crowe, Reg. No. 39,644; Stephen M. Haracz, Reg. No. 33,397; Robert G. Lancaster, Reg. No. 43,736; Warren K. MacRae, Reg. No. 37,876; Kevin C. Hooper, Reg. No. 40,402; Christopher J. Hayes, Reg. No. 41,822; Roxanna Wizorek, Reg. No. 46,110; Charles T.J. Weigell, Reg. No. 43,398; Angel Herrera, Reg. No. 46,767, of the firm of Bryan Cave LLP, Two North Central Avenue, Suite 2200, Phoenix, Arizona, 85004, telephone (602) 364-7000, facsimile (602) 364-7070, and the attorney(s) and agent(s) associated with Customer No. 23330 as its attorneys with full powers of substitution, revocation and association, to transact all business in the United States Patent and Trademark Office in connection with the above-identified patent application and any and all continuation, continuation-in-part, continued prosecution, and divisional applications thereof.

Please direct all correspondence regarding this patent application to George C. Chen, Bryan Cave LLP, Two North Central Avenue, Suite 2200, Phoenix, Arizona 85004, phone (602) 364-7000.

Motorola, Inc.

Dated: 2 Jan 02

By: William E. Koch

William E. Koch

Portfolio Manager, Motorola Labs